

Vishay Semiconductors

Standard Sinterglass Diode

Features

- · Cavity-free glass passivated junction
- · High temperature metallurgically bonded con-
- · Hermetically sealed package
- · Medium switching for improved efficiency

Mechanical Data

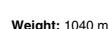
Case: Sintered glass case, G4

Terminals: Solder plated axial leads, solderable per

MIL-STD-750, Method 2026

Polarity: Color band denotes cathode end Weight: 1040 mg

Mounting Position: Any



Parts Table

Part	Type differentiation	Package
1N5550	V _{RRM} = 200 V	G4
1N5551	V _{RRM} = 400 V	G4
1N5552	V _{RRM} = 600 V	G4

Absolute Maximum Ratings

T_{amb} = 25 °C, unless otherwise specified

Parameter	Test condition	Part	Symbol	Value	Unit
Reverse voltage = Repetitive peak reverse	see electrical characteristics	1N5550	V _R =	200	V
voltage			V_{RRM}		
	see electrical characteristics	1N5551	V _R =	400	V
			V_{RRM}		
	see electrical characteristics	1N5552	V _R =	600	V
			V_{RRM}		
Maximum average forward rectified current	0.375 " (9.5 mm) lead length at $T_{amb} = 55$ °C		I _{F(AV)}	3.0	Α
Peak forward surge current	8.3 ms single half sine-wave superimposed on rated load (JEDEC Method)		I _{FSM}	100	Α
Operating and storage temperature range			T _J ,	- 55 to +	°C
			T _{STG}	175	

Maximum Thermal Resistance

T_{amb} = 25 °C, unless otherwise specified

Parameter		Symbol	Value	Unit
Typical thermal resistance 1)		$R_{\theta JA}$	22	K/W
		$R_{ hetaJL}$	12	K/W

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¹⁾ Thermal resistance from junction to ambient and from junction to lead at 0.375 " (9.5mm) lead length, with both leads mounted between heat sinks.

Electrical Characteristics

 T_{amb} = 25 °C, unless otherwise specified

Parameter	Test condition	Part	Symbol	Min	Max	Unit
Minimum reverse breakdown voltage	I _R = 50 μA	1N5550	V _(BR)	240		V
	I _R = 50 μA	1N5551	V _(BR)	460		V
	I _R = 50 μA	1N5552	V _(BR)	660		V
Maximum instantaneous forward voltage	I _F = 9.0 A		V _F		1.2	V
Maximum reverse current	V _R = V _{RRM} , T _{amb} = 25 °C		I _R		1.0	μА
	V _R = V _{RRM} , T _{amb} = 100 °C		I _R		25	μА
Maximum junction capacitance	V _R = 12 V, f = 1 MHz	1N5550	CJ		150	pF
	V _R = 12 V, f = 1 MHz	1N5551	CJ		120	pF
	V _R = 12 V, f = 1 MHz	1N5552	CJ	·	100	pF
Maximum reverse recovery time	$I_F = 0.5 \text{ A}, I_R = 1.0 \text{ A}, I_{rr} = 0.25 \text{ A}$		t _{rr}		2.0	μS

Typical Characteristics (T_{amb} = 25 °C unless otherwise specified)

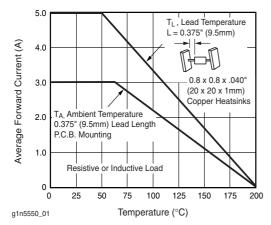


Figure 1. Forward Current Derating Curve

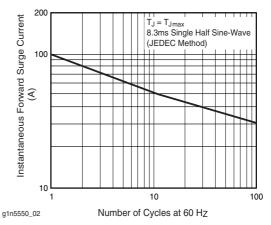


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current



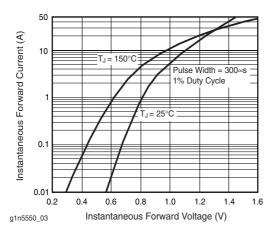


Figure 3. Typical Instantaneous Forward Characteristics

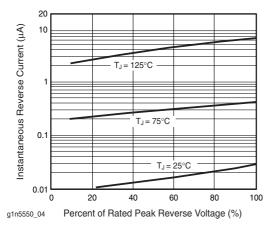


Figure 4. Typical Reverse Characteristics

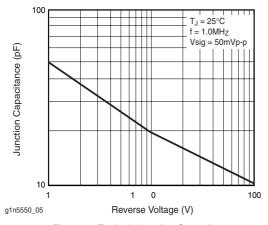
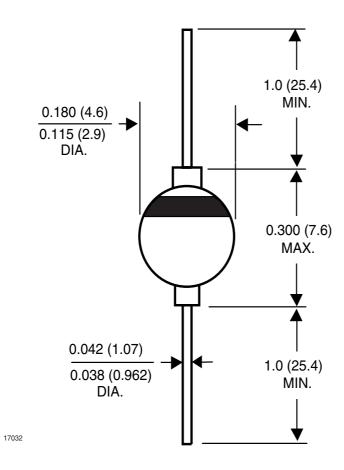


Figure 5. Typical Junction Capacitance

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Package Dimensions in Inches (mm)



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Ozone Depleting Substances Policy Statement

It is the policy of Vishay Semiconductor GmbH to

- 1. Meet all present and future national and international statutory requirements.
- 2. Regularly and continuously improve the performance of our products, processes, distribution and operatingsystems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

- 1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
- 2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
- 3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design and may do so without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use Vishay Semiconductors products for any unintended or unauthorized application, the buyer shall indemnify Vishay Semiconductors against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

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